



TE Internal #: 8-2355626-1  
Double Data Rate (DDR) 5, Board-to-Component, 288 Position,  
Surface Mount, Vertical Module Orientation, .85 mm [.033 in]  
Centerline, DIMM Sockets  
[View on TE.com >](#)

Connectors > Socket Connectors > Memory Sockets > DIMM Sockets



DRAM Type: **Double Data Rate (DDR) 5**  
Connector System: **Board-to-Component**  
Number of Positions: **288**  
Termination Method to PCB: **Surface Mount**  
Module Orientation: **Vertical**

Features

Product Type Features

|                                   |                          |
|-----------------------------------|--------------------------|
| Connector & Contact Terminates To | Printed Circuit Board    |
| DRAM Type                         | Double Data Rate (DDR) 5 |
| Connector System                  | Board-to-Component       |

Configuration Features

|                     |          |
|---------------------|----------|
| Number of Keys      | 1        |
| Number of Bays      | 2        |
| Number of Rows      | 2        |
| Number of Positions | 288      |
| Module Orientation  | Vertical |

Electrical Characteristics

|              |       |
|--------------|-------|
| DRAM Voltage | 1.1 V |
|--------------|-------|

Body Features

|                |                        |
|----------------|------------------------|
| Latch Color    | Black                  |
| Latch Material | High Temperature Nylon |



|                                |                        |
|--------------------------------|------------------------|
| PCB Retention Feature Material | Stainless Steel        |
| Connector Profile              | Standard               |
| Ejector Material Color         | Black                  |
| Module Key Type                | DRAM                   |
| Ejector Location               | Both Ends              |
| Ejector Material               | High Temperature Nylon |
| Ejector Type                   | Rotary                 |

Contact Features

|   |                |
|---|----------------|
| Contact Underplating Material                           | Nickel         |
| Socket Style  | DIMM           |
| Contact Mating Area Plating Material Thickness          | .76 µm[30 µin] |
| PCB Contact Termination Area Plating Material Thickness | 3 µm[120 µin]  |
| Contact Mating Area Plating Material                    | Gold (Au)      |
| Memory Socket Type                                      | Memory Card    |
| Contact Base Material                                   | Copper Alloy   |
| PCB Contact Termination Area Plating Material           | Tin            |
| Contact Current Rating (Max)                            | 1.5 A          |

Termination Features

|                                |                 |
|--------------------------------|-----------------|
| Insertion Style                | Direct Insert   |
| Termination Post & Tail Length | .89 mm[.035 in] |
| Termination Method to PCB      | Surface Mount   |

Mechanical Attachment

|                          |             |
|--------------------------|-------------|
| Connector Mounting Type  | Board Mount |
| PCB Mount Retention      | With        |
| Mount Angle              | Vertical    |
| PCB Mount Retention Type | Tab         |
| Mating Alignment Type    | 1 Key       |
| Mating Alignment         | With        |
| PCB Mount Alignment Type | None        |

Housing Features

|                    |                        |
|--------------------|------------------------|
| Housing Color      | Black                  |
| Housing Material   | High Temperature Nylon |
| Centerline (Pitch) | .85 mm[.033 in]        |



Dimensions

|                         |                  |
|-------------------------|------------------|
| Profile Height from PCB | 21.3 mm[.083 in] |
| Row-to-Row Spacing      | 3 mm[.118 in]    |

Usage Conditions

|                             |                            |
|-----------------------------|----------------------------|
| Operating Temperature Range | -55 – 105 °C[-67 – 221 °F] |
|-----------------------------|----------------------------|

Operation/Application

|                     |                 |
|---------------------|-----------------|
| Circuit Application | High Speed Data |
|---------------------|-----------------|

Industry Standards

|                        |          |
|------------------------|----------|
| UL Flammability Rating | UL 94V-0 |
|------------------------|----------|

Packaging Features

|                    |            |
|--------------------|------------|
| Packaging Quantity | 640        |
| Packaging Method   | Box & Tray |

Product Compliance

For compliance documentation, visit the product page on TE.com>

|   |  |
|---|--|
| EU RoHS Directive 2011/65/EU                  | Compliant  |
| EU ELV Directive 2000/53/EC                   | Compliant  |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold  |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JAN 2025 (247)<br>Candidate List Declared Against: JUNE 2024 (241)<br>Does not contain REACH SVHC |
| Halogen Content                               | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free  |
| Solder Process Capability                     | Not reviewed for solder process capability   |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides



on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) ‘Guidance on requirements for substances in articles’ posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts

TE Part # 8-2355632-1  
DDR5 DIMM NATURAL HSG AND NATURAL LATCH

Customers Also Bought

TE Part #2441848-1  
CA, MCIO 8X STR TO MCIO 8X STR

TE Part #1-2351053-3  
LGA4677/LGA4710 SOCKET COVER

TE Part #1-2324271-4  
LEFT SEGMENT LGA4189-4 SOCKET-P4 FOR ODM

TE Part #2-2347090-1  
SOCKET 4677 DG1.0 FOR ODM

TE Part #2339800-1  
MATENET 2X3 HEADER, 90DEG, CODE A

TE Part #9-1438789-2  
38way Hybrid .040/2.8 Header Assy

TE Part #1-2324271-3  
RIGHT SEGMENT LGA4189-4 SOCKETP4 FOR ODM

TE Part #1-2397198-1  
SOCKET 4710 FOR ODM

TE Part #8-2355632-1  
DDR5 DIMM NATURAL HSG AND NATURAL LATCH

TE Part #8-2355644-1  
DDR5 DIMM SMT\_blue hsg&blue latch

Documents

Product Drawings

DDR5 DIMM BLACK HSG AND BLACK LATCH

English



CAD Files

Customer View Model

[ENG\\_CVM\\_CVM\\_8-2355626-1\\_A.3d\\_stp.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_8-2355626-1\\_A.3d\\_igs.zip](#)

English

3D PDF

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_8-2355626-1\\_A.2d\\_dxf.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

[Application Specification](#)

English